

Title (en)  
Resin composition for extruded forms

Title (de)  
Harzzusammensetzung für Strangpressformen

Title (fr)  
Composition de résine pour formes extrudées

Publication  
**EP 0679685 B1 19980916 (EN)**

Application  
**EP 95106178 A 19950425**

Priority  

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- JP 12017794 A 19940601

Abstract (en)  
[origin: EP0679685A1] A resin composition for extruded forms is disclosed, comprising (A) an ethylene resin and (B) a copolymer of ethylene and an alpha -olefin having 4 to 40 carbon atoms having (a) a density (D) of 0.86 to 0.935 g/cm<sup>3</sup>, (b) a melt flow rate of 1 to 50 g/10 min, (c) an elution curve showing a single peak at a peak temperature of not higher than 100 DEG C, said elution curve being obtained by temperature rising elution fractionation (TREF), in which substantial elution may occur at temperatures other than said peak temperature, and (d-1) an integral elution volume of not less than 90% at an elution temperature of 90 DEG C in TREF, or (d-2) an elution volume Y, in percent by weight based on the total weight of component B, in TREF satisfying the following condition: (1) Y <= 10 when the density D of component B is not less than 0.91 g/cm<sup>3</sup>, or (2) Y <= -4500D + 4105 when the density D of component B is less than 0.91 g/cm<sup>3</sup>, provided that Y <= 100. The resin composition is free from unevenness in resin blending and has excellent transparency, low-temperature heat sealability, heat sealing strength, hot tack, strength, with a balance in processing between ductility and neck-in and which is useful for production of laminates, films or sheets.

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Cited by  
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